

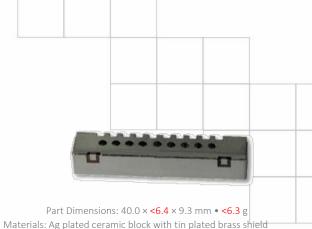


Features

- Low Loss with High Rejection
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade TDD Pico-cells.



Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	8.0 Watt max
Peak Input Power	-	-	-	80 Watt max
Input-Output Response				
Passband Insertion Loss (100 MHz avg)	3800-3900	1.7 dB	2.0 dB max	2.0 dB max
Passband Ripple (over 100 MHz)	3800-3900	1.5 dB	1.7 dB max	1.8 dB max
Passband Return Loss	3800-3900	14 dB	13 dB min	12 dB min
Attenuation:	1-2690	65 dB	60 dB min	60 dB min
	2691-3600	45 dB	40 dB min	40 dB min
	3601-3780	23 dB	21 dB min	20 dB min
	3920-4099	23 dB	21 dB min	20 dB min
	4100-5149	45 dB	40 dB min	40 dB min
	5150-5925	45 dB	40 dB min	40 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

Specification Allowance					
Insertion Loss	0.1 dB				
Return Loss	1.0 dB				
Attenuation	1.0 dB				

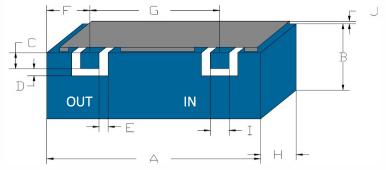
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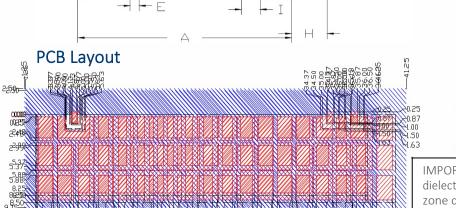


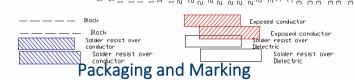
Preliminary - MMB385A

3.8-3.9GHz MMB Series TDD BPF

Mechanical Drawing







Nominal Tolerance Dim. (mm) (±mm or Max) 40.0 Α max В <4.8 max C 1.0 0.13 0.5 D 0.13 Ε 0.5 0.13 F 4.5 0.25 G 31.0 0.13 Н 9.3 max Ι 1.0 0.13 J 1.4 0.2

Combined 40mm & 50mm universal footprint PCB layout is also available.

IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Electrical Response

